

Please enter the following amended claims:

- huty*
D1
1. (Amended) A semiconductor apparatus comprising:
metal bumps formed so as to connect to a circuit pattern of a semiconductor device and
a resin film formed on a circuit pattern forming surface of said semiconductor device so as to seal
spaces between the metal bumps and be lower in height than a height of the metal bumps, the surfaces of
the metal bumps projecting out from the resin film being cleaned;
wherein said metal bumps are solder bumps and solder layers different in composition from said
solder bumps are formed at the surfaces of the solder bumps projecting out from the resin film.
- B2*
2. (Amended) The semiconductor apparatus as set forth in claim 1, wherein the surfaces of the
metal bumps projecting out from the resin film are cleaned of components causing a rise of a connection
resistance and a drop in a joint strength at least at connection interfaces.
5. (Amended) The semiconductor apparatus as set forth in claim 1, wherein said solder bumps
are comprised of high melting point solder and said solder layer is comprised of eutectic solder.
6. (Amended) The semiconductor apparatus as set forth in claim 2, wherein said solder bumps
are comprised of high metal point solder and said solder layers are comprised of a eutectic solder.

Please add the following new Claim 25:

- D1*
B3
25. (New) A semiconductor apparatus comprising:
a semiconductor chip having a circuit pattern disposed thereon;
a plurality of solder bumps formed on said semiconductor chip and connecting to said circuit
pattern, said solder bumps forming spaces therebetween;

a resin film disposed on said semiconductor chip and said solder bumps, said resin film being disposed in the spaces between solder bumps such that upper surfaces of said solder bumps protrude from said resin layer;

wherein said upper surfaces of said solder bumps are cleaned of impurities;

a eutectic solder layer disposed on said cleaned upper surfaces of said solder bumps;

a mounting board;

a plurality of lands formed on said mounting board and aligned opposite said solder bumps; and

a precoated solder layer disposed on said lands;

wherein said eutectic solder layer of said solder bumps and said precoated solder layer join said upper surfaces of said solder bumps to said lands of said mounting board such that a stacked structure is obtained.

Cont'd
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D1

→ board 20 is precoated by a solder layer 17
(pg 7, line 4)

→ solder precoated on the connection lands
of mounting board

→ eutectic solder precoat'd on the lands